## **MA4S111**

## Silicon epitaxial planar type

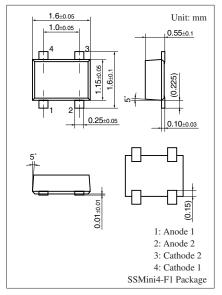
For switching circuits

#### ■ Features

- Allowing high-density mounting
- Short reverse recovery time t<sub>rr</sub>
- Small terminal capacitance C<sub>t</sub>

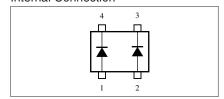
### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit
Reverse voltage		$V_R$	80	V
Maximum peak reverse voltage		$V_{RM}$	80	V
Forward current	Single	$I_F$	100	mA
	Double		75	
Repetitive peak	Single	$I_{FRM}$	225	mA
forward current	Double		170	
Junction temperature		T <sub>j</sub>	150	°C
Operating ambient temperature		T <sub>opr</sub>	-30 to +85	°C
Storage temperature		$T_{stg}$	-55 to +150	°C



Marking Symbol: M1B

#### Internal Connection

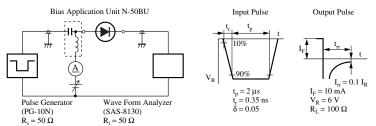


### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

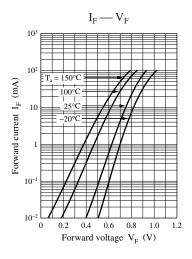
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\mathrm{F}}$	$I_F = 100 \text{ mA}$		0.95	1.2	V
Reverse voltage	$V_R$	$I_R = 100 \mu A$	80			V
Reverse current	$I_R$	$V_R = 75 \text{ V}$			100	nA
Terminal capacitance	C <sub>t</sub>	$V_R = 0 V, f = 1 MHz$		0.6	2	pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			3	ns
		$I_{rr} = 0.1 I_R$ , $R_L = 100 \Omega$				

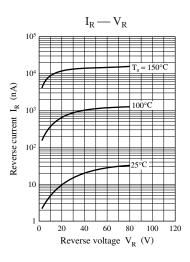
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring method for diodes.

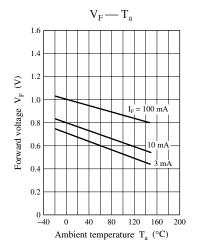
- 2. Absolute frequency of input and output is 100 MHz.
- 3. \*: t<sub>rr</sub> measurement circuit

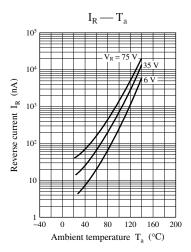


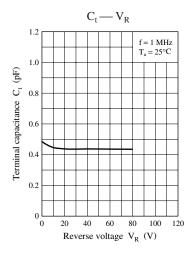
## **Panasonic**

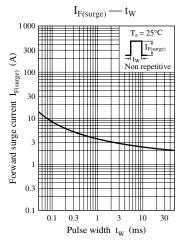












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